



3W STEREO CLASS-D AUDIO AMPLIFIER AND CLASS AB HEADPHONE DRIVER WITH DC VOLUME CONTROL, NON-CLIP POWER LIMIT AND UVP

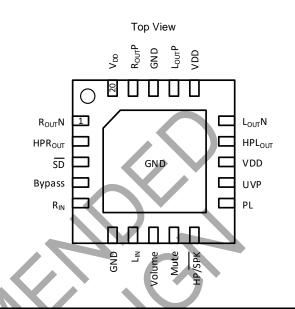
Description

The PAM8019 is a Stereo 3W Class D audio power amplifier for driving bridged-tied speakers and includes a Stereo Class AB amplifier for driving headphones. The advanced 64 step DC volume control minimizes external components allowing simple and accurate volume control over the gain range of +20dB (Volume = 0V) to -60dB (Volume = 5V).

Integrated non-clip power limit technology suppresses output automatically with programmable power limit, improving the sound quality and helping to protect the speakers. Programmable undervoltage protection (UVP) can be used to shut down the PAM8019 at a pre-determined voltage level helping to eliminate speaker pop by shutting down before the power supply collapses.

The PAM8019 is available in the power efficient and space saving U-QFN4040-20 package.

Pin Assignments



Features

- 3W Stereo Class D Amplifier with Class AB Headphone Amplifier
- Filter Free and Low EMI Architecture
- Operating Voltage: 2.8V to 5.5V
- Low Quiescent Current of 7mA at a VDD of 5V
- 64 Step DC Volume Control with Hysteresis from -60dB to +20dB
- Output Power
 - Class D Amplifier THD+N = 1%
 - $V_{DD} = 5V$, Load = 4 Ω ; Po = 2.4W / Load = 8 Ω ; Po = 1.4W
 - Class D Amplifier THD+N = 10%
 - $V_{DD} = 5V$, Load = 4 Ω ; Po = 3.0W / Load = 8 Ω ; Po = 1.7W
 - Class AB Headphone Amplifier
 V_{DD} = 5V, Load = 32Ω; P_Q = 60mW
- Speaker or Headphone Select
- Non-Clip Power Limit (NCPL) Function
- OVP and Programmable UVP Protection
- Thermal and Overcurrent Protection with Auto-Recovery
- Power Enhance Package U-QFN4040-20
- Lead Free and Green Devices Available (RoHS Compliant)
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please <u>contact us</u> or your local Diodes representative. <u>https://www.diodes.com/quality/product-definitions/</u>
- Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 - 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

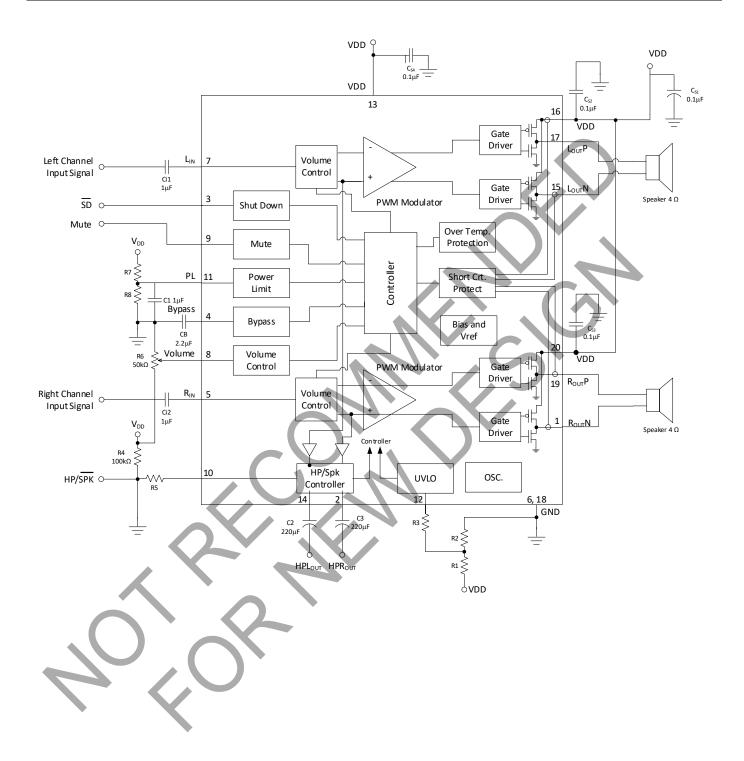
Applications

- LCD monitors and TVs
- Projectors/All-in-one computers
- Portable/active speakers
- Portable DVD players/Game machines



PAM8019

Typical Applications Circuit

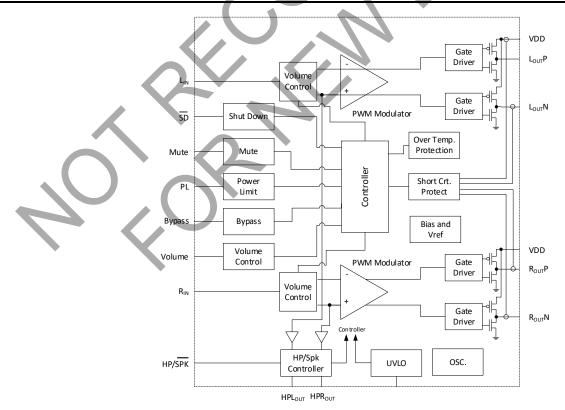




Pin Descriptions

Pin Number	Pin Name	Function	
3	SD	Full Chip Shutdown Control Input (Active Low)	
4	Bypass	Bias Voltage for Power Amplifier	
5	Rın	Negative Input of Right Channel Power Amplifier	
6, 18	GND	Ground Connection	
7	L _{IN}	Negative Input of Left Channel Power Amplifier	
8	Volume	Internal Gain Setting Input Connect to VDD which Set Max. Gain = +20dB	
9	Mute	Mute Control Signal Input (Active High)	
10	HP/SPK	Output Mode Control Input High for Headphone Mode and Low for Speaker Mode	
11	PL	Power Limit Reference Voltage, see Application Information section for further details	
12	UVP	Undervoltage Protection Input See Application Information section for further details	
13, 16, 20	VDD	Supply Voltage	
14	HPLOUT	Headphone – Left Channel Output	
2	HPROUT	Headphone – Right Channel Output	
15	LoutN	Power Amplifier – Left Channel Negative Output	
17	LoutP	Power Amplifier – Left Channel Positive Output	
19	R _{OUT} P	Power Amplifier – Right Channel Negative Output	
1	RoutN	Power Amplifier – Right Channel Positive Output	
PAD	GND	Connect to ground (recommended) or No Connect.	

Functional Block Diagram





Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.) (Note 4)

Symbol	Parameter	Rating	Unit
V _{DD}	Supply Voltage V _{DD}	-0.3 to 6.0	V
Vin	Input Voltage LIN, RIN, SD, Mute, HP/SPK	-0.3 to V _{DD} + 0.3	V
TJ	Maximum Junction Temperature	+150	
Tstg	Storage Temperature Range	- 65 to +150	°C
T _{SDR}	Maximum Soldering Temperature Range, 5 Seconds	+300	

Note: 4. Stresses greater than those listed under *Absolute Maximum Ratings* can cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to *Absolute Maximum Ratings* for extended periods can affect device reliability.

Recommended Operating Conditions (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter		Max	Unit
VDD	Supply Voltage Range		2.8 to 5.5	V
M ()	High-Level Threshold Voltage	SD, Mute	2 to V _{DD}	V
Vін	High-Level Threshold Voltage	HP/SPK	0.8 x VDD to VDD	V
		SD, Mute	0 to 0.8	V
VIL	Low-Level Threshold Voltage	HP/SPK	0 to 1.0	V
VICM	Common Mode Input Voltage		1 to V _{DD} - 1	V
TA	Ambient Operation Temperature Range		-40 to +85	°C
TJ	Junction Temperature Range		-40 to +125	

Thermal Information (@TA = +25°C, unless otherwise specified.)

Symbol	Parameter		Typical Value	Unit
θја	Thermal Resistance – Junction to Ambient	U-QFN4040-20	45	°C/W
өлс	Ambient Operation Temperature Range	U-QFN4040-20	7	°C/W





Electrical Characteristics (@T_A = +25°C, V_{DD} = 5V, Gain = Max., R_L = 8 Ω , unless otherwise specified.)

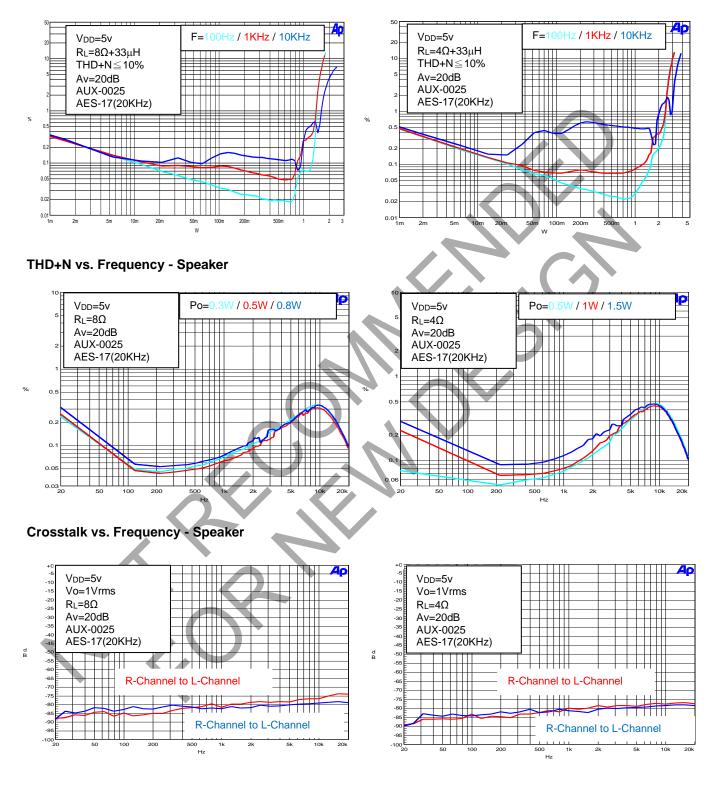
Symbol	Parameter	Condition	Min	Тур	Max	Unit	
Vdd	Supply Voltage Range	_	2.8	_	5.5	V	
Speaker Mo	de						
lq	Quiescent Current (BTL)	VMUTE = 0, VSD = 5V, No Load	_	7	_	mA	
lq	Quiescent Current (SE)	VMUTE = 0, VSD = 5V, No Load	_	4	_	mA	
Імите	Mute Current (BTL)	VMUTE = 0, VSD = 5V, No Load	_	3	_	mA	
IMUTE	Mute Current (SE)	V _{MUTE} = 0, V _{SD} = 5V, No Load		4		mA	
Isd	Shutdown Current	VMUTE = 0, VSD = 0V, No Load	_	_	1	μA	
fosc	Oscillator Frequency		200	250	300	kHz	
RI	Input Resistance (BTL)	Gain = 20dB	_		33	kΩ	
RI	Input Resistance (SE)	Gain = 3.5dB	_		56	kΩ	
Vos	Output Offset Voltage	No load	_	10	_	mV	
		V _{DD} = 5.5V, I _{DS} = 0.8A P MOSFET		0.26			
		VDD = 5.5V, IDS = 0.8A N MOSFET	$\left(- \right)$	0.19	-		
R _{DS(ON)}	Drain-Source On-State Resistance	VDD = 4.5V, IDS = 0.6A P MOSFET VDD = 4.5V, IDS = 0.6A		0.28		Ω	
		$V_{DD} = 4.5V$, $I_{DS} = 0.6A$ N MOSFET $V_{DD} = 3.6V$, $I_{DS} = 0.4A$	_	0.21	-		
		$\frac{P}{P} = 3.6V, I_{DS} = 0.4A$ $\frac{P}{DD} = 3.6V, I_{DS} = 0.4A$	-	0.29			
		N MOSFET		0.21			
İ START UP	Startup Time from Shutdown	Bypass Capacitor, $C_B = 2.2 \mu F$		1.72	_	S	
Po	Output Power	THD+N = 10%, f = 1kHz, RI = 8Ω	1.5	1.7	—	w	
-	•	THD+N = 10%, f = 1kHz, RI = 4 Ω	2.8	3.0	_		
THD+N	Total Harmonic Distortion Plus	$RI = 8\Omega$, $Po = 0.8W$, $f = 1kHz$	_	0.08 —		%	
	Noise	RI = 4Ω, Po = 1.6W, f = 1kHz	_	0.08	_		
PSRR	Power Supply Ripple Rejection	Input AC-GND, f = 1kHz, VPP = 200mV	_	- 61	_	dB	
CS	Channel Separation	Vpd = 1W, f = 1kHz		-82	_	dB	
η	Efficiency	Po = 1.7W, f = 1kHz, RI = 8Ω	85	90	_	— %	
		$P_0 = 3W, f = 1kHz, RI = 4\Omega$	80	88	_		
VN	Noise	Input AC-GND, A-weighting	—	180	—	μV	
		Non A-weighting	—	270	—	μV	
SNR	Signal Noise Ratio	f = 20 to 20kHz, THD = 1%	—	83	—	dB	
lead Phone							
Vos	Output Offset Voltage	No load	_	2.5	_	V	
Po	Output Power	THD+N = 1%, RI = 32Ω, f = 1kHz	—	60	—	mW	
THD+N	Total Harmonic Distortion Plus Noise	RI = 32Ω, Po = 50mW, f = 1kHz	—	0.02	—	%	
PSRR	Power Supply Ripple Rejection	Input AC-GND, f = 1kHz, VPP = 200mV	_	75	_	dB	
CS	Channel Separation	$P_0 = 1W$, f = 1kHz	_	-87	_	dB	
M	Nisiaa	Input AC-GND, A-weighting	_	74	_	μV	
VN	Noise	Non A-weighting		58		μV	
SNR	Signal Noise Ratio	f = 20 to 20kHz, THD = 1%		89	_	dB	
Control Sec	tion						
VIH	SD Input High	—	1.4	—	—	V	
VIL	SD Input Low		_	_	0.6	V	
VMH	Mute Input High	—	1.4	—	—	V	
Vml	Mute Input Low		_	_	0.6	V	
OTP	Overtemperature Protection		_	+150	_	°C	
OTH	Overtemperature Hysteresis			+108	_	°C	



PAM8019

Typical Performance Characteristics

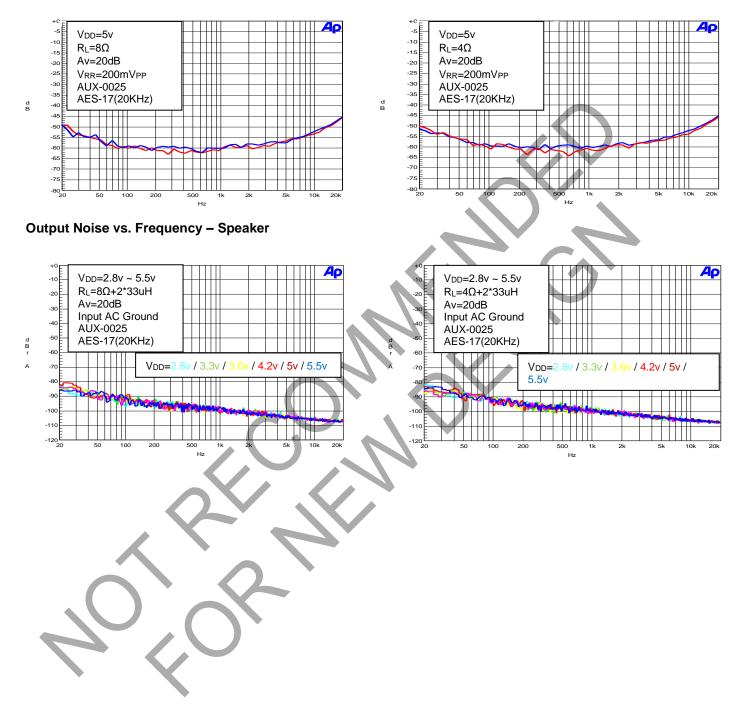
THD+N vs. Output Power - Speaker





Typical Performance Characteristics (continued)

PSRR vs. Frequency





Typical Performance Characteristics (continued)

			Head Phone					Head Phone
		Power Amp	Amp Gain				Power Amp	Amp Gain
Step	DC Volume (V)	Gain (dB)	(dB)		Step	DC Volume (V)	Gain (dB)	(dB)
1	0.000 to 0.201	20	3.51		33	2.462 to 2.533	6.7	-7.11
2	0.202 to 0.275	19.6	3.22		34	2.534 to 2.605	6.4	-7.43
3	0.276 to 0.347	19.2	2.94		35	2.606 to 2.678	6	-7.76
4	0.348 to 0.419	18.8	2.66		36	2.679 to 2.751	5.7	-8.09
5	0.420 to 0.491	18.4	2.39		37	2.752 to 2.823	5.3	-8.42
6	0.492 to 0.563	18	2.12		38	2.824 to 2.897	4.9	-8.76
7	0.564 to 0.633	17.6	1.85		39	2.898 to 2.969	4.6	-9.09
8	0.634 to 0.701	17.1	1.46		40	2.970 to 3.043	4.2	-9.43
9	0.702 to 0.771	16.6	1.07		41	3.044 to 3.114	3.8	-9.77
10	0.772 to 0.849	16.1	0.69		42	3.115 to 3.186	3.5	-10.1
11	0.850 to 0.929	15.6	0.32		43	3.187 to 3.259	3.1	-10.46
12	0.930 to 1.005	15.1	-0.05		44	3.260 to 3.332	2.7	-10.81
13	1.006 to 1.079	14.6	-0.41		45	3.333 to 3.403	2.3	-11.16
14	1.080 to 1.153	14.2	-0.77		46	3.404 to 3.476	2	-11.52
15	1.154 to 1.225	13.7	-1.12		47	3.477 to 3.551	1.6	-11.88
16	1.226 to 1.297	13.3	-1.47		48	3.552 to 3.621	1.2	-12.24
17	1.298 to 1.371	12.9	-1.82		49	3.622 to 3.695	0.8	-12.62
18	1.372 to 1.443	12.5	-2.16		50	3.696 to 3.767	0.4	-12.99
19	1.444 to 1.517	12	-2.5	V	51	3.768 to 3.839	0	-13.38
20	1.518 to 1.589	11.6	-2.84		52	3.840 to 3.909	-1	-14.37
21	1.590 to 1.661	11.2	-3.18		53	3.910 to 3.979	-2.1	-15.42
22	1.662 to 1.733	10.8	-3.51		54	3.980 to 4.045	-3	-16.3
23	1.734 to 1.807	10.5	-3.84		55	4.046 to 4.116	-5	-18.23
24	1.808 to 1.879	10.1	-4.17		56	4.117 to 4.195	-7	-20.16
25	1.880 to 1.951	9.7	-4.5		57	4.196 to 4.273	-9	-22.08
26	1.952 to 2.025	9.3	-4.82		58	4.274 to 4.347	-10.9	-23.96
27	2.026 to 2.097	8.9	-5.16		59	4.348 to 4.421	-17	-30.01
28	2.098 to 2.169	8.6	-5.48		60	4.422 to 4.493	-22.8	-35.83
29	2.170 to 2.243	8.2	-5.8		61	4.494 to 4.565	-29	-41.98
30	2.244 to 2.315	7.8	-6.13		62	4.566 to 4.637	-33.5	-46.46
31	2.316 to 2.389	7.5	-6.45		63	4.638 to 4.708	-39.5	-52.58
32	2.390 to 2.461	7.1	-6.78		64	4.709 to 5.000	-60	-92.95
	X							

Table 1. DC Volume Control



Application Information

Non-Clip Power Limit (NCPL) Function

When output reaches the maximum power setting value, the NCLP circuits will decrease the gain to prevent the output waveform from clipping helping to prevent speaker damage and maximizing audio performance. The PL pin is used to set and control the NCPL function.

AGC Function	Output Power			
V _{DD} to V _{DD} x 0.45 or PL pin floating	NCPL function disabled			
V _{DD} x 0.45 to V _{DD} x 0.27	Po = [[8(1/2 V _{DD} - VPL) ²] / RI] x 0.95			
V _{DD} x 0.27 to GND	$P_0 = 2.3W$ (Max. output power 4Ω) $P_0 = 1.2W$ (Max. output power 8Ω)			

Table 2. NCPL Setting Threshold vs. Output

Mute Operation

The Mute pin is an input for controlling the Class-D output state of the PAM8019. A logic low on this pin enables the outputs and logic high on this pin disables the outputs. This pin may be used to quickly disable or enable the outputs without a volume fade. Quiescent current is listed in the *Electrical Characteristic* table. The Mute pin can be left floating due to the internal pulldown.

Shutdown Operation

In order to reduce power consumption while not in use, the PAM8019 contains shutdown circuit to turn off the amplifier's bias circuit. The amplifier is turned off when logic low is placed on the SD pin. The SD pin can be left floating due to the internal pullup.

Undervoltage Protection

External undervoltage detection can be used to shut down the PAM8019 before an input device can generate a pop. The shutdown threshold at the UVP pin is 1.2V. The user selects a resistor divider to obtain the shutdown threshold and hysteresis for the specific application.

The threshold can be determined as below: With the condition: R3 >> R1//R2

VUVP = [1.2-(6μA x R3)] x (R1+R2) / R2 Hysteresis = 5μA x R3 x (R1+R2) / R2

Power Supply Decoupling

The PAM8019 is a high-performance CMOS audio-amplifier that requires adequate power supply decoupling to ensure the THD and PSRR are as low as possible. Power supply decoupling also prevents oscillation caused by long leads between the amplifier and the speaker. The optimum decoupling is achieved by using two capacitors of different types that target different types of noise on the power supply leads. A good Low-Equivalent-Series-Resistance (ESR) ceramic-capacitor of typically 0.1μ F is recommended to be placed as close as possible to the V_{DD} pin to filter the higher frequency transients, spikes or digital hash on the line. Filtering lower-frequency noise signals a large capacitor of 10μ F or greater should be placed near the audio amplifier.

Input Capacitor (CI)

It is desirable to use a large input capacitor but in applications where the speaker lacks the ability to reproduce signals below 100Hz to 150Hz it may be possible to minimize CI without effecting system performance. Input Capacitor (CI) and Input Resistance (RI) of the amplifier form a high-pass filter with the corner frequency determined equation below:

fc = 1 / 2πRI x CI

In addition to system cost and size, click and pop performance is affected by the size of the coupling capacitors. A larger in/out coupling capacitor requires more charge to reach its quiescent DC voltage (Normally 1/2 V_{DD}). This charge comes from the internal circuit via the feedback and is more likely to create pops upon device enable. Minimizing the capacitor size based on necessary low frequency response can minimize the turn on pop.

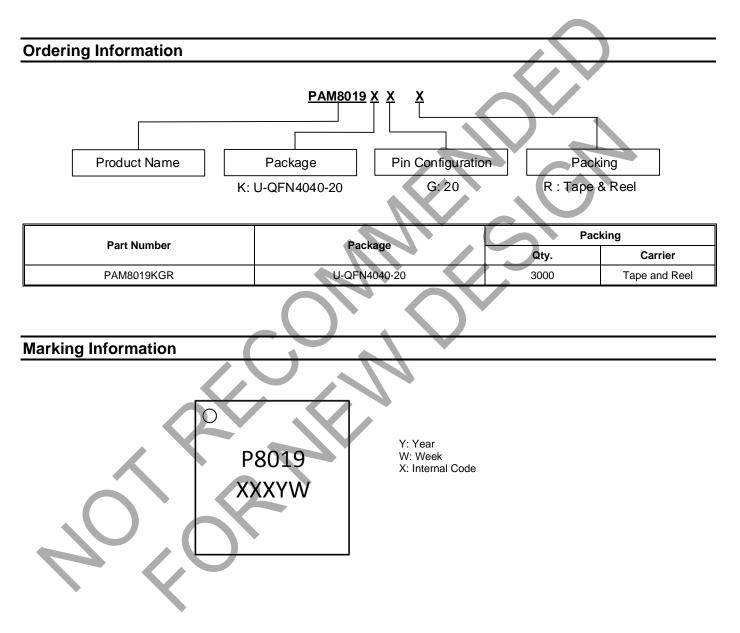


Application Information (continued)

Bypass Capacitor (CBYP)

Bypass Capacitor (C_{BYP}) is the most critical capacitor and serves several important functions. During startup or recovery from shutdown mode, C_{BYP} determines the rate at which the amplifier starts up. The second function is to reduce noise produced by the power supply caused by coupling into the output signal. The noise is from the internal analog reference to the amplifier, which appears as degraded PSRR and THD+N.

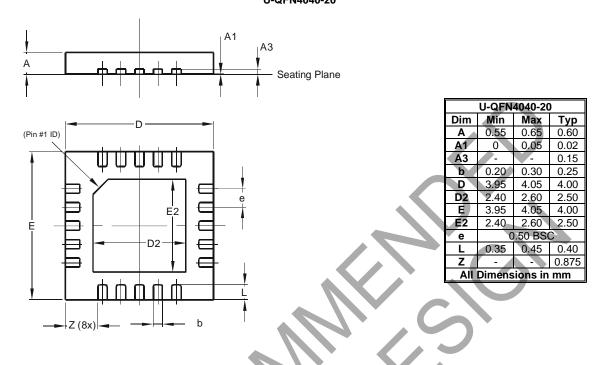
A ceramic bypass capacitor (C_{BYP}) of 0.47µF to 1.0µF is recommended for the best THD and noise performance. Increasing the bypass capacitor reduces clicking and popping noise from power on/off and when entering and leaving shutdown.





Package Outline Dimensions

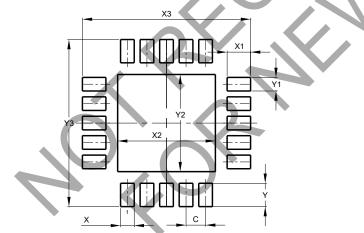
Please see http://www.diodes.com/package-outlines.html for the latest version.



Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.





Dimensions	Value (in mm)
С	0.500
Х	0.350
X1	0.600
X2	2.500
X3	4.300
Y	0.600
Y1	0.350
Y2	2.500
Y3	4.300



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